FOR IMMEDIATE RELEASE

Press Release

SMTA International 2016 is 2 weeks away!
Visit YINCAE BOOTH # 129
September 27th & 28th

(Albany, NY) 09/12/2016 – SMTA International is 2 weeks away! The tradeshow will take place at the Donald Stephens Convention Center in Rosemont, IL, from September 27th to 28th. YINCAE hopes you will stop by our Booth 129 to learn more about YINCAE and the innovative products we have to offer.

Dr. Wusheng Yin, president of YINCAE Advanced Materials, will be speaking at the conference and presenting “Room Temperature Fast Flow Reworkable Underfill for LGA”. This presentation will be held on Wednesday, September 28th at 10:30AM in room FSA3.

YINCAE offers a variety of exclusive materials, including adhesives, TIM, and materials for board, package, and wafer level applications; many of which have been adopted by leading contract manufacturers and Tier 1 microelectronic suppliers. YINCAE is the first to develop lead-free Solder Joint Encapsulants Adhesives for wafer level, flip chip, PoP, BGA, LGA… YINCAE offers Solder Joint Encapsulant Adhesives for low, medium, and high temperature solder alloy applications for individualized needs. YINCAE Advanced Materials hopes you will join us at the conference to learn about YINCAE and the solutions offered.

YINCAE invites you to visit us at Booth #129 to learn about our material solutions. You can find more information by visiting our website at: www.yincae.com

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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